



(11) **EP 1 615 261 B8**

(12) **CORRECTED EUROPEAN PATENT SPECIFICATION**

(15) Correction information:
Corrected version no 1 (W1 B1)
Corrections, see
Bibliography INID code(s) 72

(51) Int Cl.:
H01L 21/67^(2006.01) H01L 21/673^(2006.01)
H01L 21/687^(2006.01)

(48) Corrigendum issued on:
18.09.2019 Bulletin 2019/38

(86) International application number:
PCT/JP2004/003442

(45) Date of publication and mention
of the grant of the patent:
08.05.2019 Bulletin 2019/19

(87) International publication number:
WO 2004/090967 (21.10.2004 Gazette 2004/43)

(21) Application number: **04720720.4**

(22) Date of filing: **15.03.2004**

(54) **SEMICONDUCTOR WAFER HEAT TREATMENT JIG**

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(84) Designated Contracting States:
DE FR

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(30) Priority: **02.04.2003 JP 2003099709**

(43) Date of publication of application:
11.01.2006 Bulletin 2006/02

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